



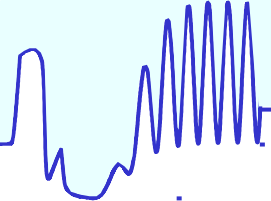
Solar PV Modules Optical Characterization

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- 
- a. Electroluminescence/ Photoluminescence
 - b. EL/PL Imaging
 - c. Spectral response measurement
Internal and External quantum Efficiency.
 - d. Thermography

Luminescence

- Electroluminescence:
Light emitted under electrical excitation, such as in a light emitting diode
- Photoluminescence:
Light emitted under optical excitation, such as in
Fluorescent Lamp

Excess Carrier Density

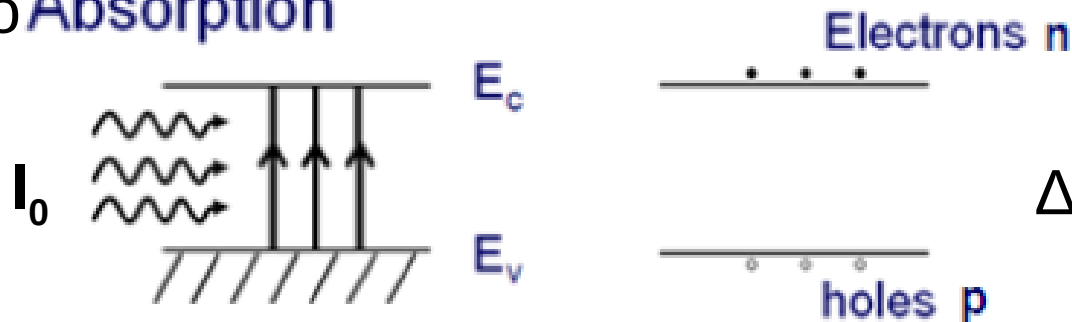
a. Excitation : Generation of Excess Electrons and Holes

$$n = n_0 + \Delta n, \quad p = p_0 + \Delta p$$

i) Electrical Injection :

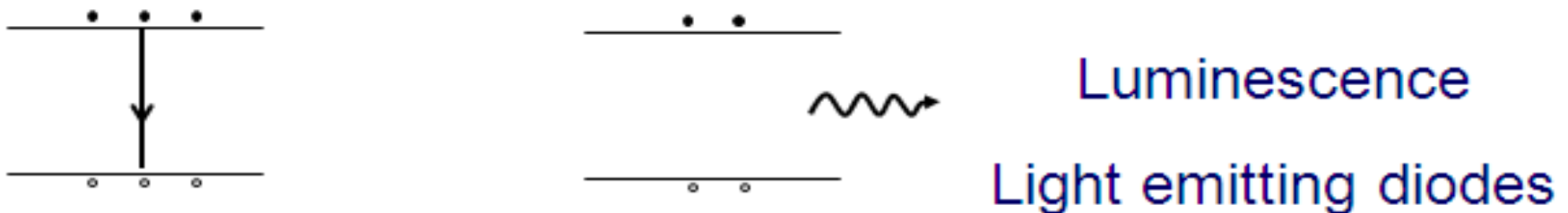
$$\Delta n = \Delta p = (I / qA W) \cdot \tau_{\text{eff}}$$

ii) Photo**Absorption**

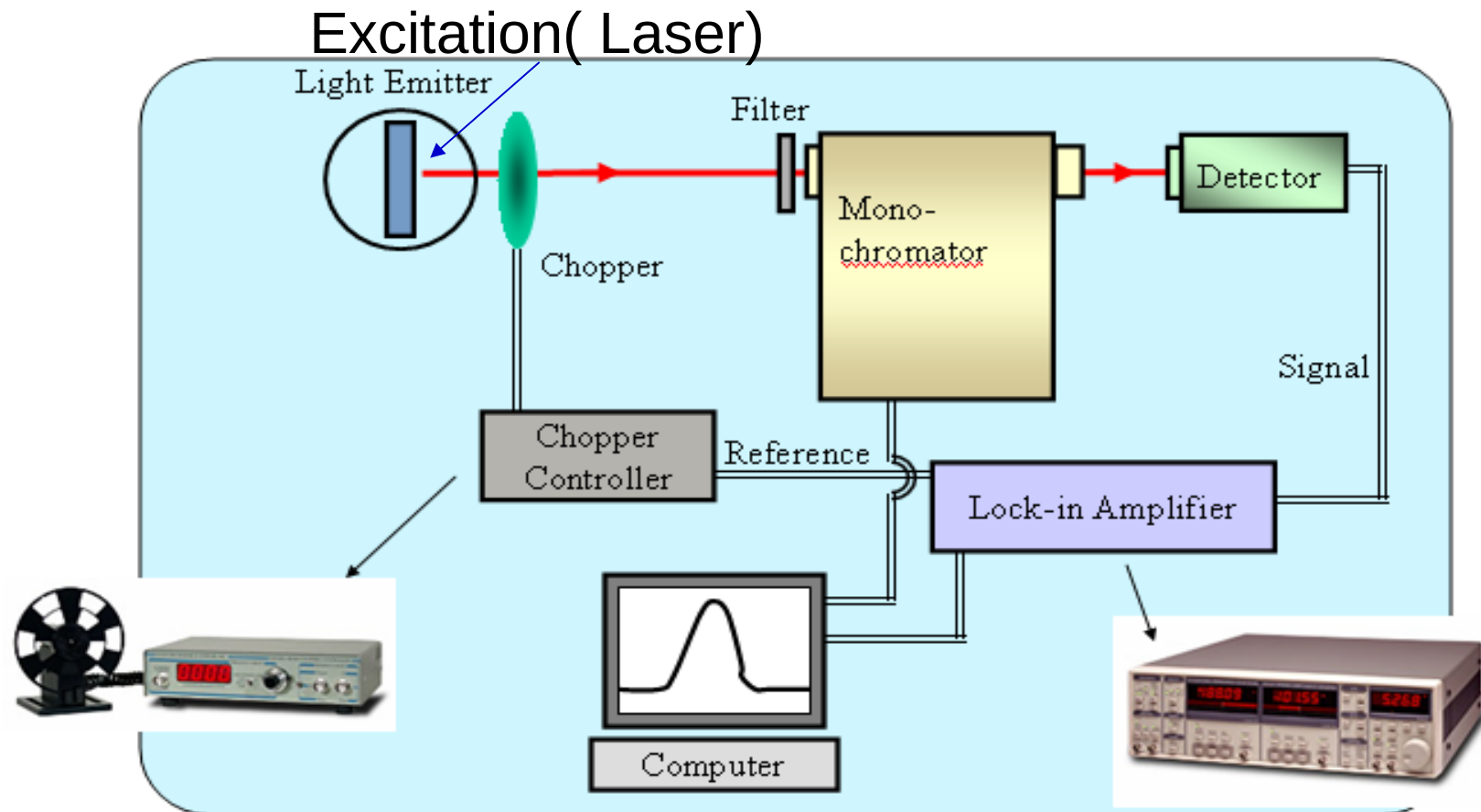


$$\Delta n = \Delta p = G \tau = (\alpha I_0 / h\nu) \tau$$

b) Recombination (Spontaneous emission)



Luminescence Spectrum measurement



Monochromator : To separate the different wavelength components in the light beam

Detector : To convert the light into an electrical signal

Lock-in amplifier : To detect the signal while rejecting noise

Spectrum of Light Emitted by Silicon Solar Cell

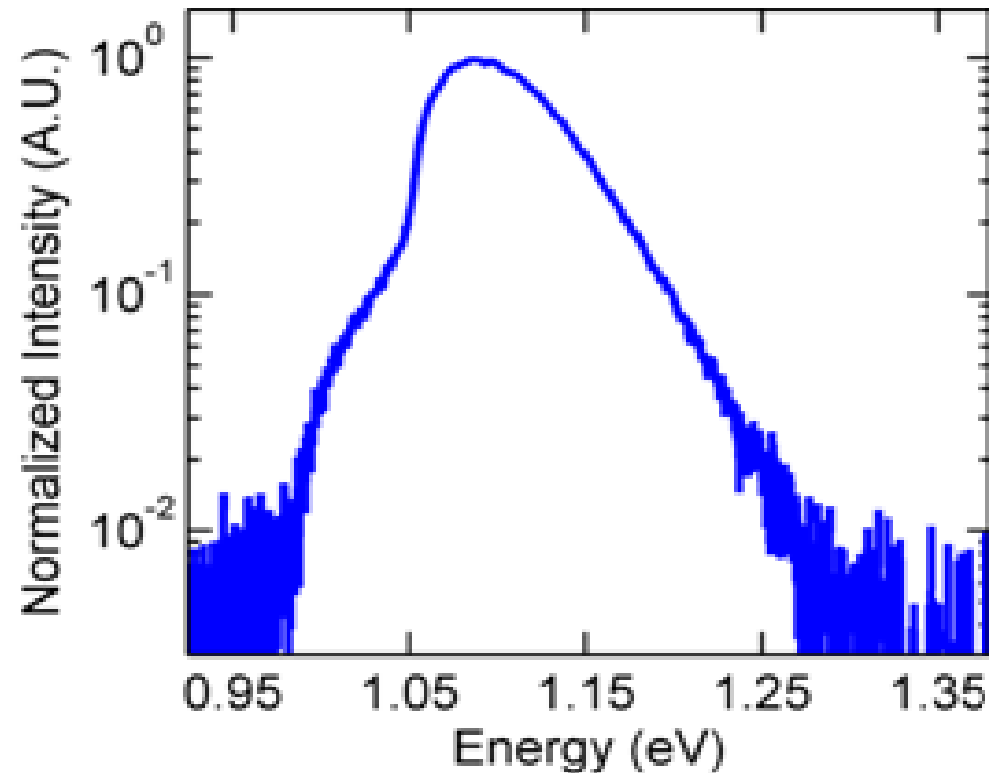


Fig.3. Intensity of the EL signal normalized to the peak value and plotted as a function of energy.

Band to Band Recombination Processes

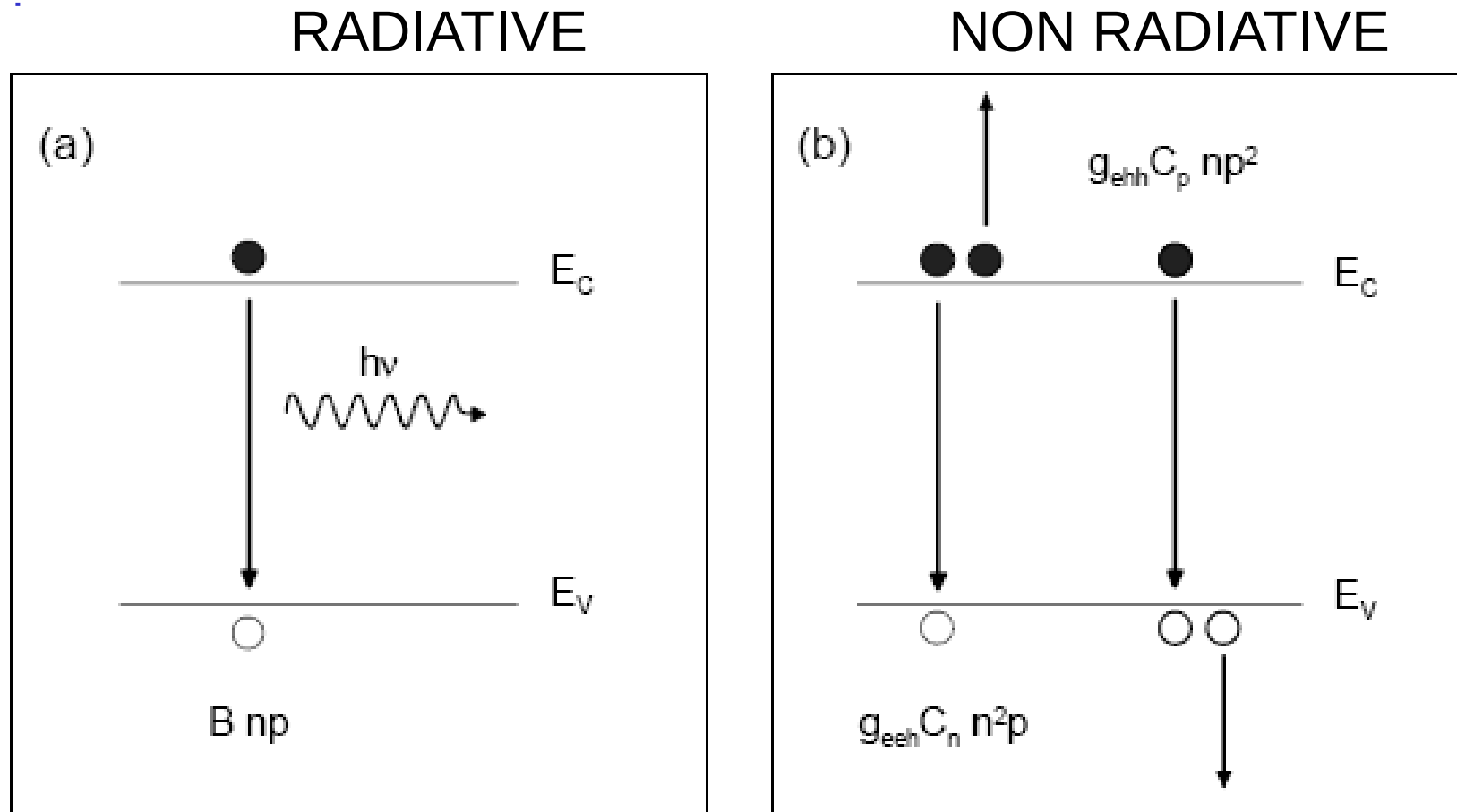
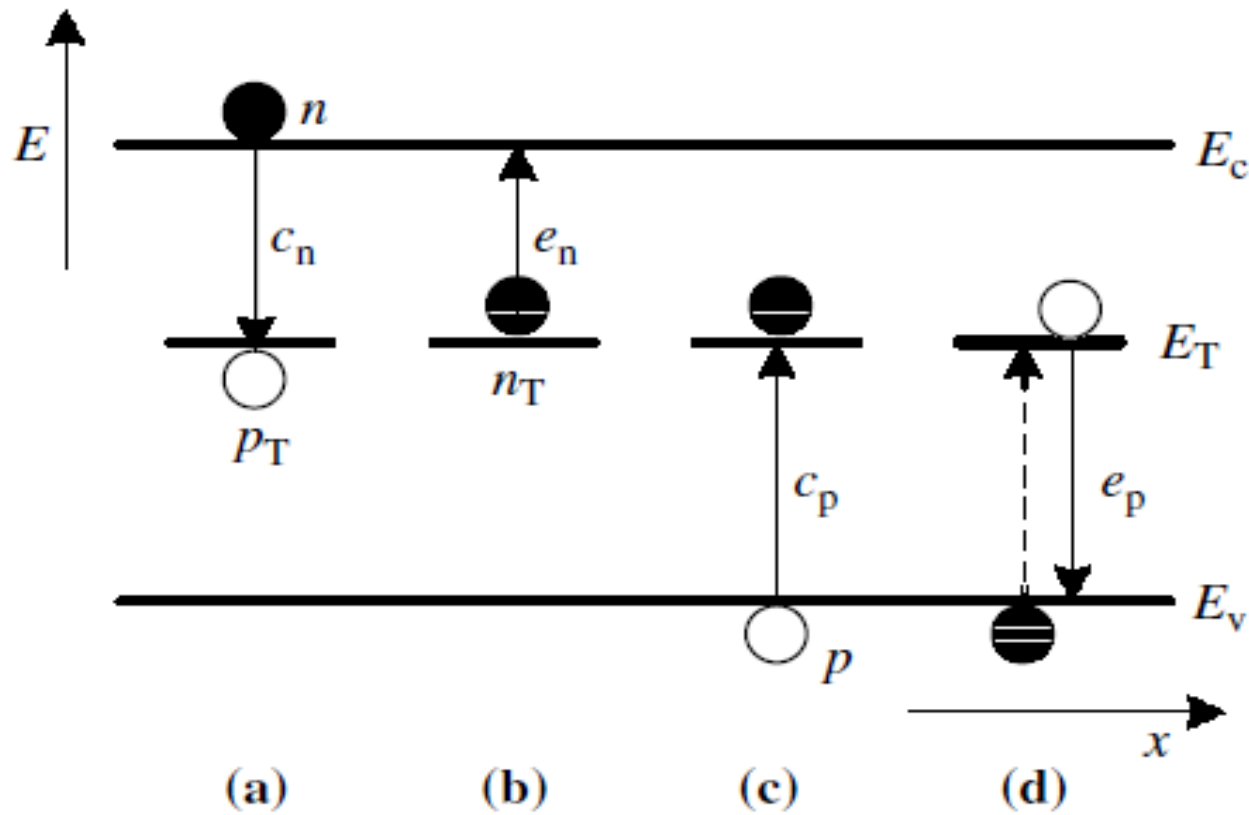


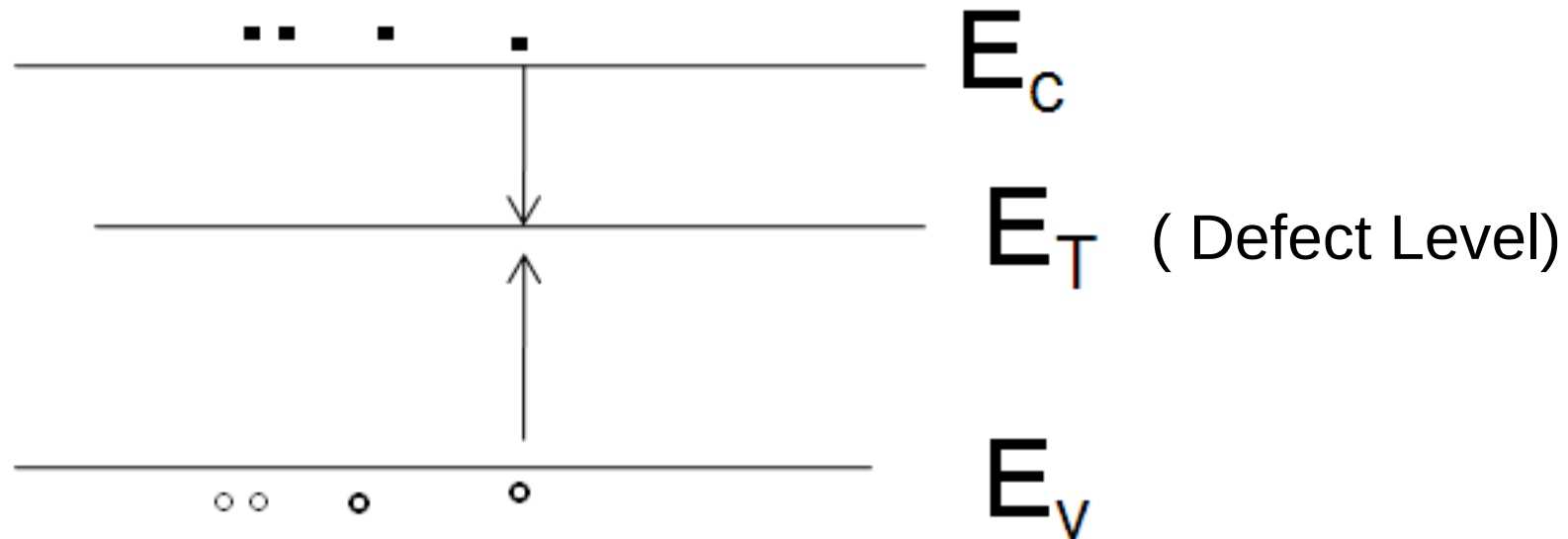
Fig. 1.12. Schematic diagram of intrinsic recombination mechanisms: (a) radiative band-band recombination and (b) Auger band-band recombination.

Interactions between Bands and Defect Level E_T



Recombination via Defect Level

Non – Radiative Recombination at bulk defects, surfaces
Shockley-Read-Hall (SRH)



$$R = \frac{(np - n_i^2)}{\tau_{po}(n + n_1) + \tau_{no}(p + p_1)}$$

$$\tau_{po} = \frac{1}{c_p N_t}$$

$$\tau_{no} = \frac{1}{c_n N_t}$$

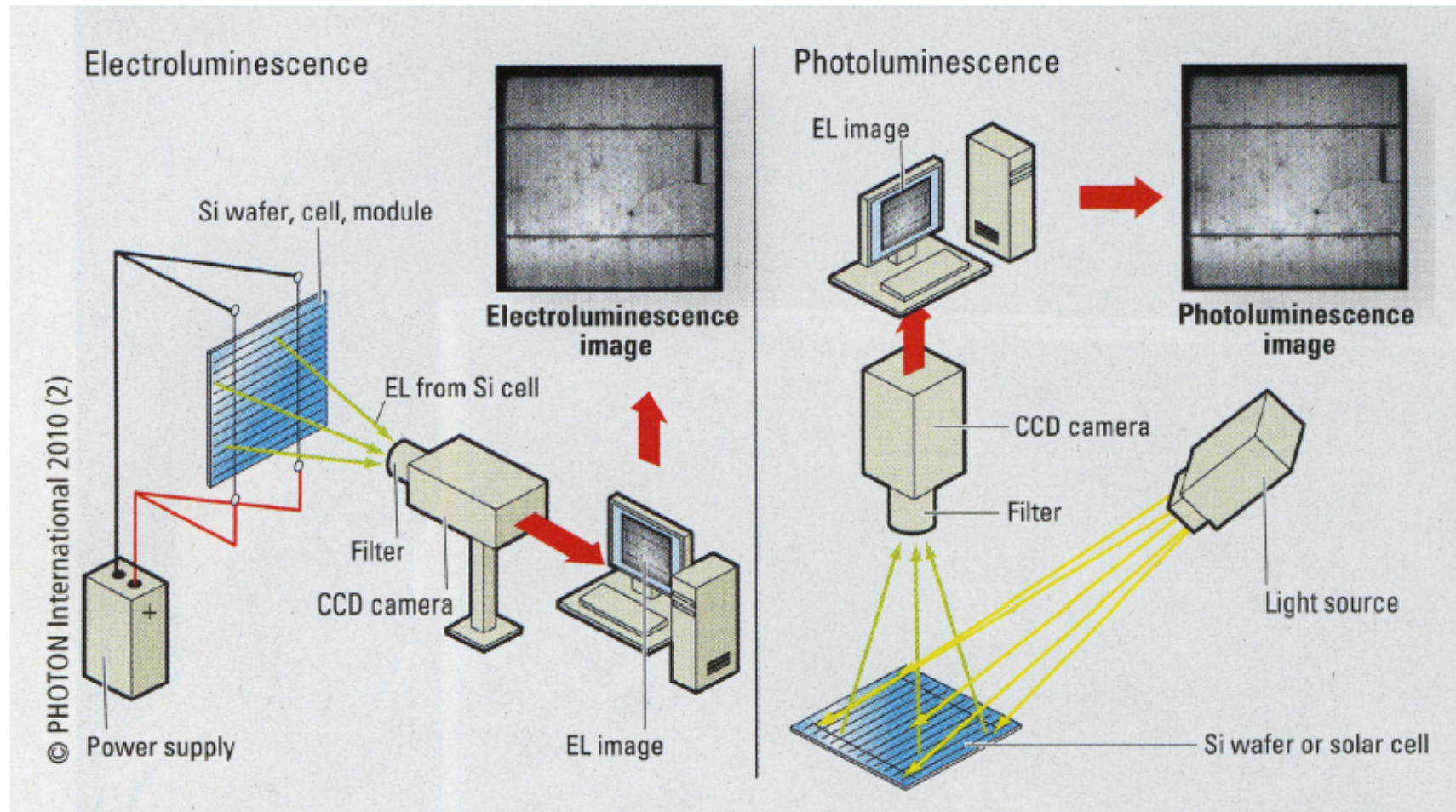
Emission Efficiency of Silicon

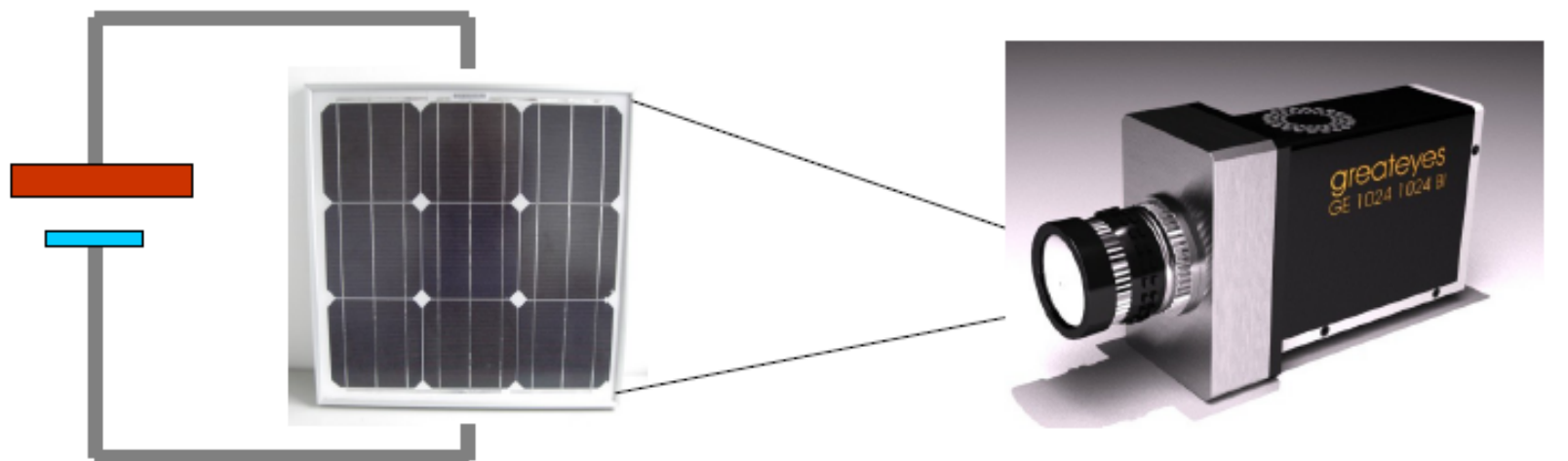
- Radiative Recomb Rate = $\Delta n / \tau_R$
For Silicon $\tau_R \sim 20$ msec
- Total Recombination Rate = $\Delta n / [1/\tau_R + \tau_{NR}]$
- Emission Efficiency = $\tau_{NR} / \tau_R + \tau_{NR}$
 $= 10^{-3}$ for Si

depending on τ_{NR} . (If there are defects, τ_{NR} will be smaller and emission will reduce)

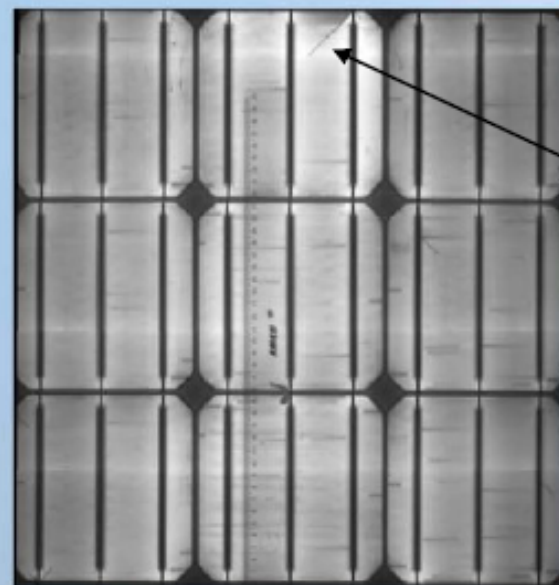
EL/PL Imaging

Measurement Principle – How does it work ?





Normal visible Image.



Crack

Electroluminescence

PL Imaging : Cell Fabrication Monitoring

1 ohm-cm FZ
Silicon
4 inch wafer
Quarters
Trupke et al
2006 IEEE PVSC

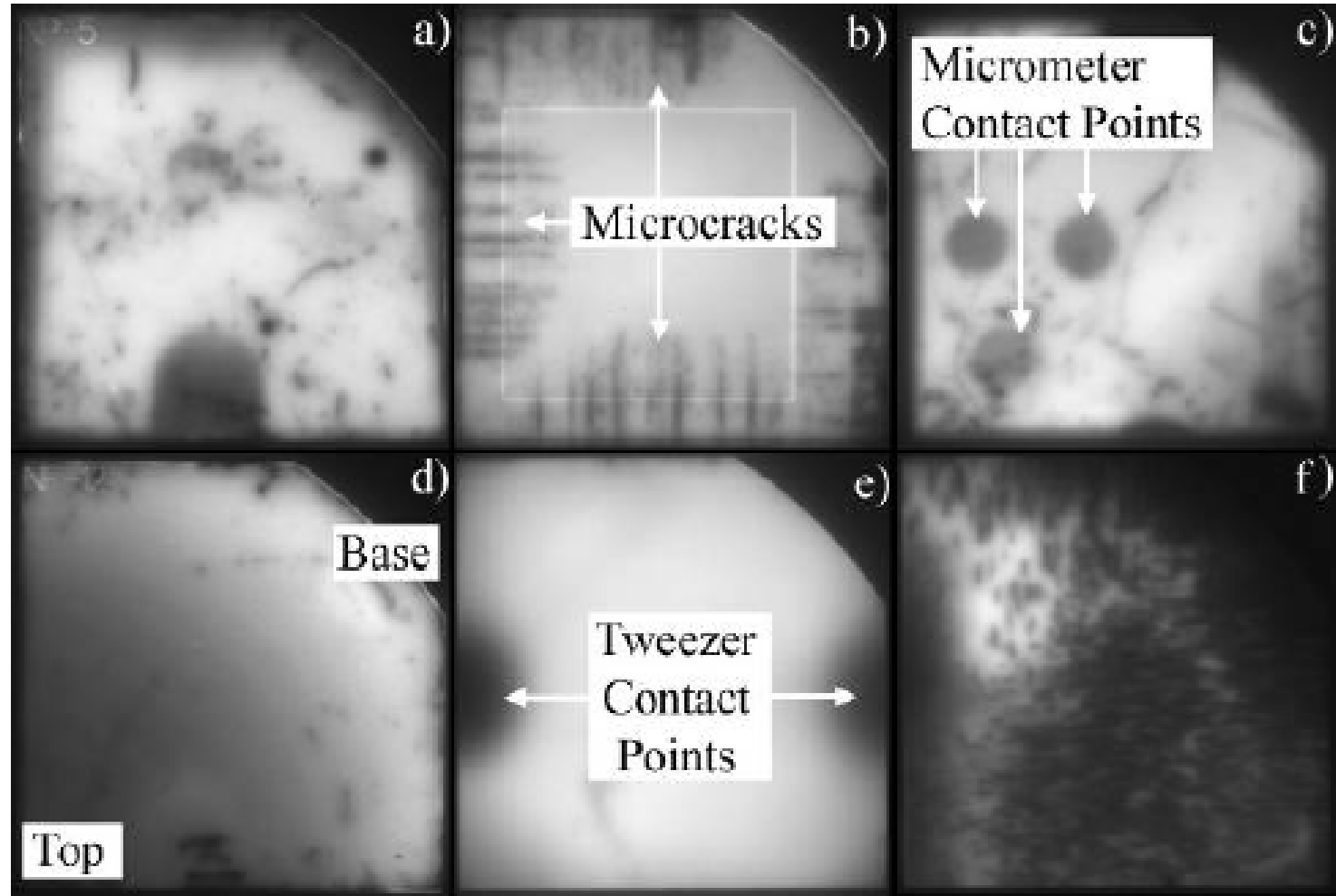
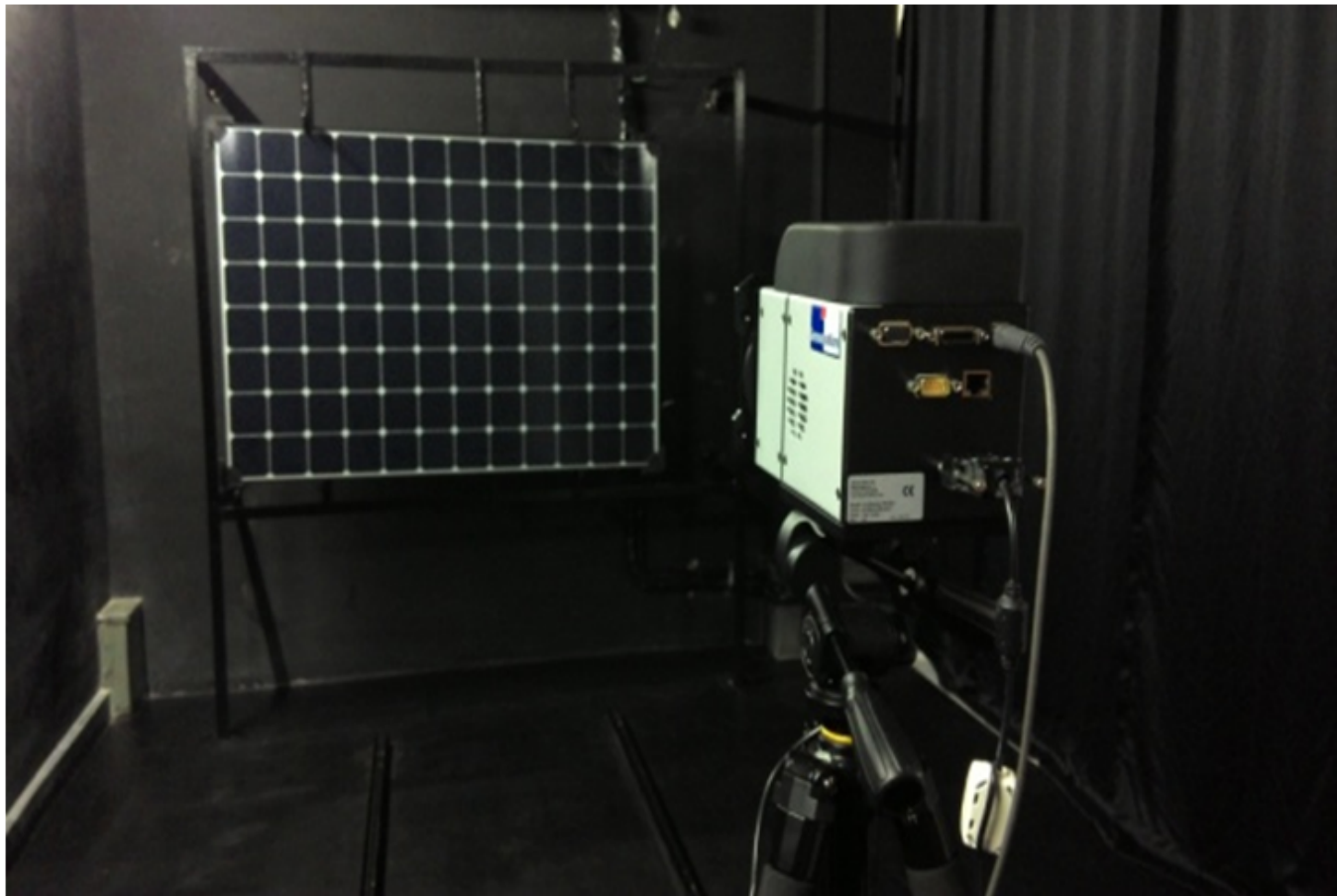


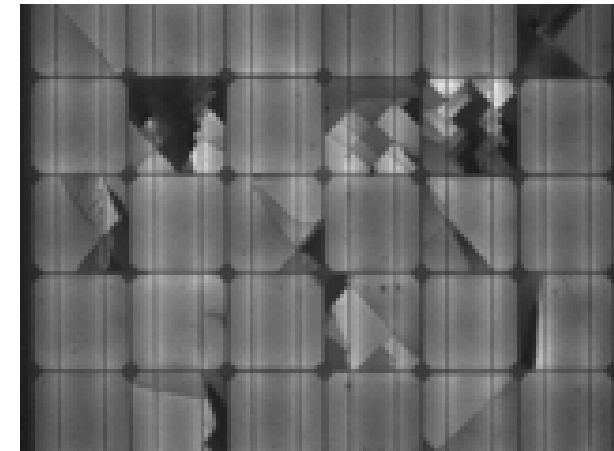
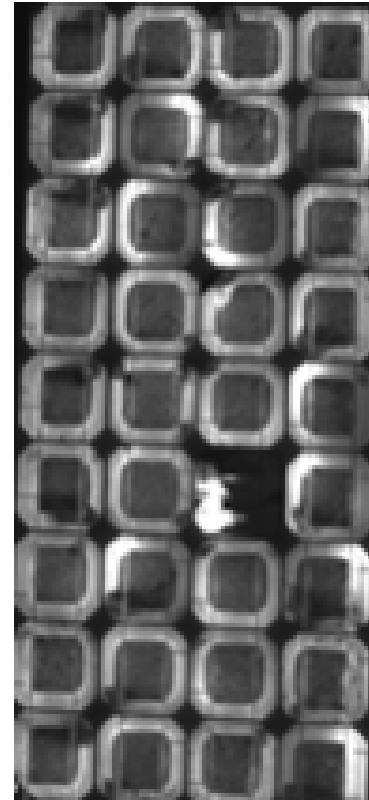
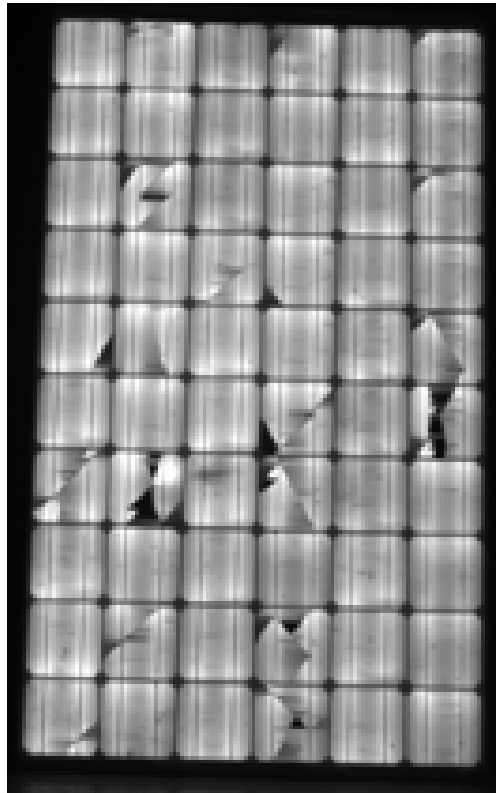
Fig.1 Various examples of process induced defects

- a) Effect of a dent in substrate holder , b) Poor Laser Scribing and cleaving , c) Effect of measurement by micrometer, d) Effect of temperature gradient across wafer during furnace anneal
e) Wafer handling with clean plastic tweezers , f) unintentionally contaminated wafer

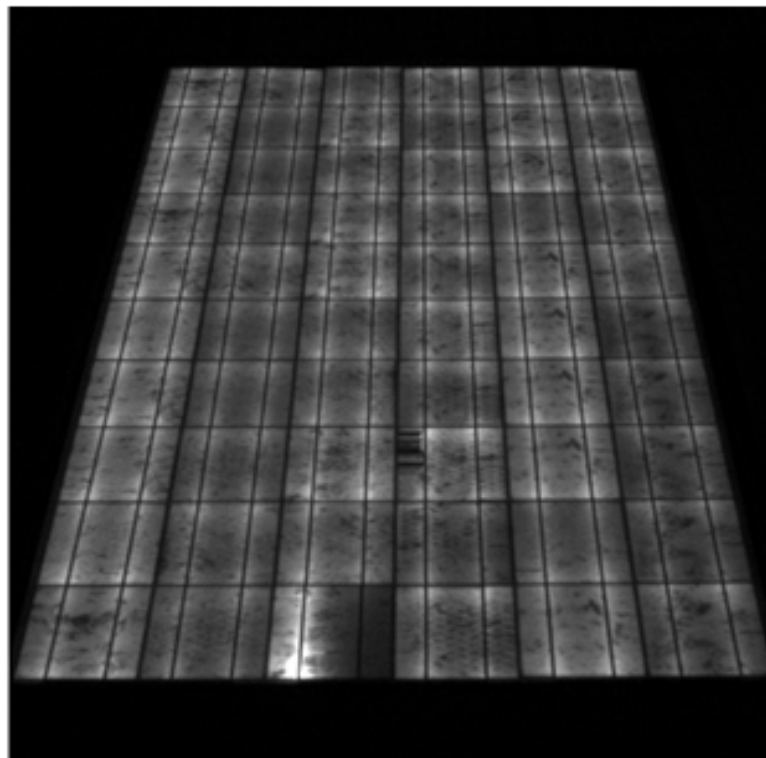
Standard method OF EL Imaging Measurement of Module



- Importance of Electroluminescence image
 - Quick method to find out the latent defects in the solar cells, particularly cracks and inactive regions



EL Image C-Si Module



6 in x 6 in cell
 $J_{sc} \sim 36.8 \text{ mA/cm}^2$

EL with
 $I_F \sim 1.3 I_{sc}$

Av Voc per cell
0.615 V

Exposure time 180 sec

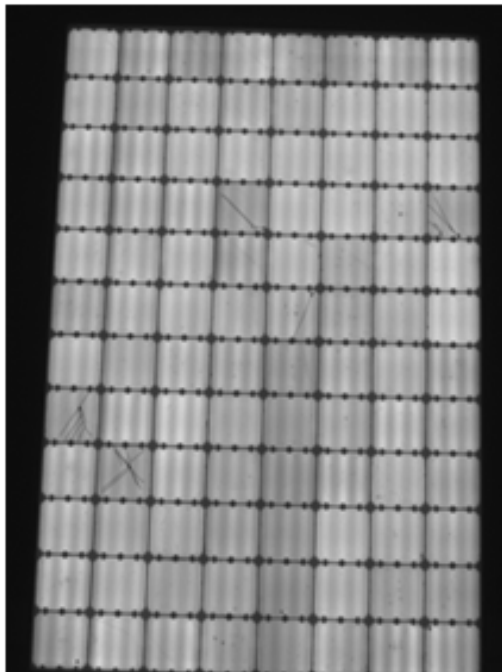
Name plate Data

P_{max} (Watts): 230 W, V_{oc} (Volts): 36.9 V (60 Cells)

I_{sc} (Amp): 8.56 A, I_{max} (Amp): 7.52 A,

V_{max} (Volts): 30.60 V

EL Image Sun Power Module

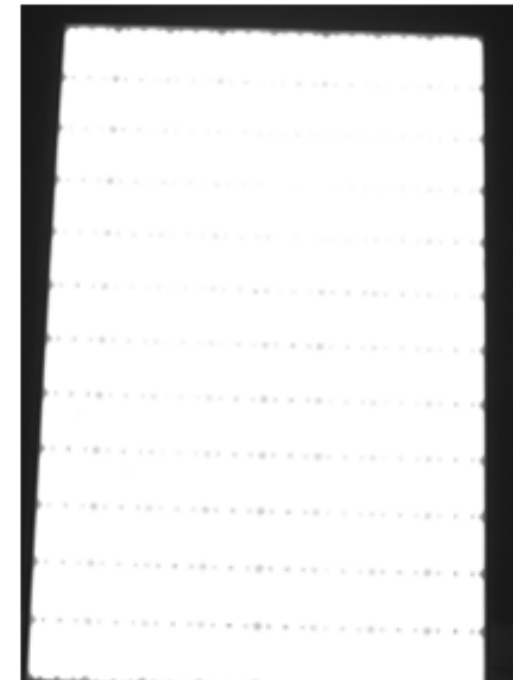


Exposure time 20 sec

5 in x 5 in cell
 $J_{sc} \sim 40 \text{ mA/cm}^2$

EL with
 $I_F = 1.3 I_{sc}$

Av Voc per cell
 0.676 V



Exposure time 60 sec

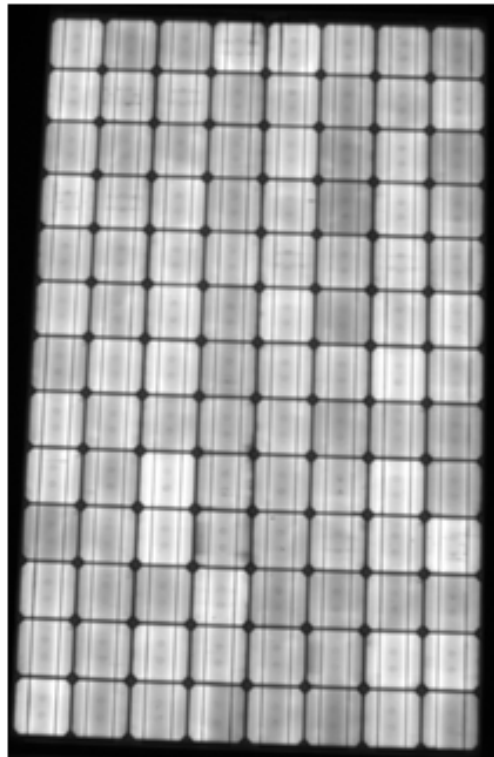
Name plate Data

Pmax (Watts): 327 W, Voc (Volts): 64.9 V (96 cells)

Isc (Amp): 6.46 A, Imax (Amp): 5.98 A,

Vmax (Volts): 54.7 V

EL Image HIT Module

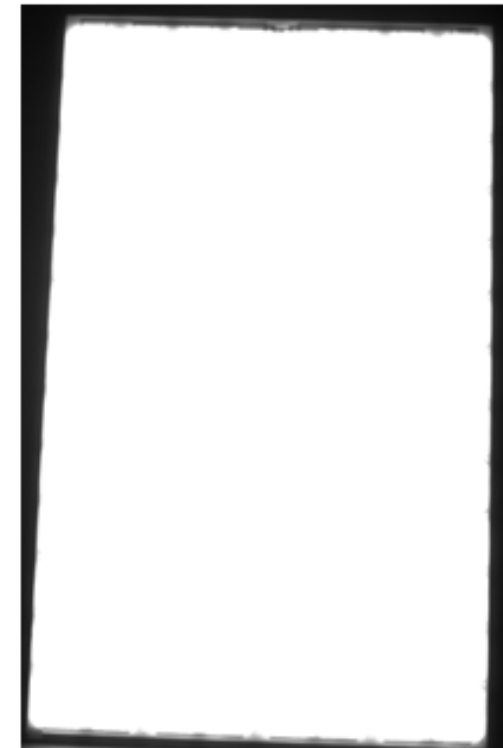


Exposure time 6 sec

10cmx10cm cell
 $J_{sc} \sim 37.9 \text{ mA/cm}^2$

EL with
 $I_F = 1.3 I_{sc}$

Av Voc per cell
 0.708 V



Exposure time 60 sec

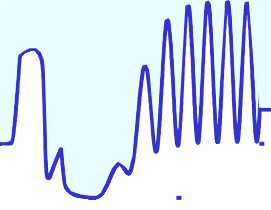
Name plate Data

P_{max} (Watts): 210 W, V_{oc} (Volts): 73.6 V (104 Cells)

I_{sc} (Amp): 3.79 A, I_{max} (Amp): 3.52 A,

V_{max} (Volts): 59.7 V

Rajeev, IIT Bombay



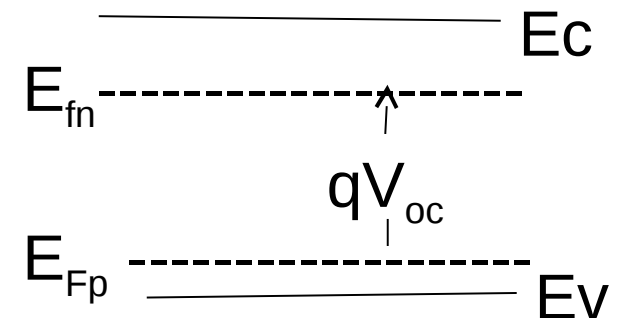
V_{oc} is governed by Excess Carrier Density Generated by Light

$$V_{oc} = E_{Fn} - E_{Fp} ,$$

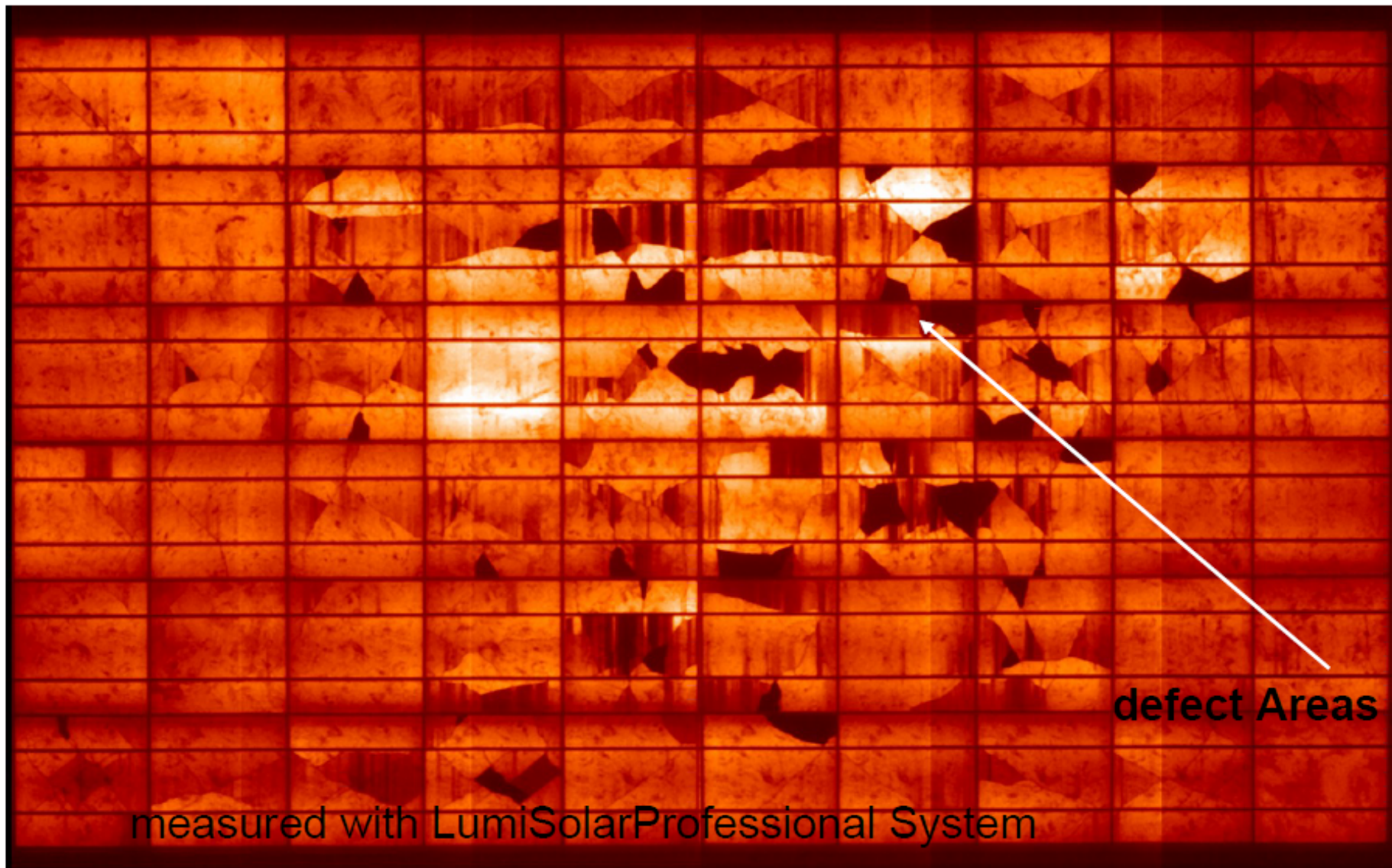
$$E_C - E_{Fn} = kT \ln(N_c / (\Delta n + n_0)) ,$$

$$E_{Fp} - E_v = kT \ln(N_v / (N_a + \Delta p))$$

$$\begin{aligned} (\Delta n + n_0) (N_a + \Delta p) &= n_i^2 \exp [qV_{oc} / kT] \\ &= n_i^2 \exp [(E_{fn} - E_{fp}) / kT] \\ V_{oc} &\sim kT/q [\ln (\Delta n \cdot N_a) / n_i^2] \\ &\sim kT/q [\ln (G\tau \cdot N_a) / n_i^2] \end{aligned}$$

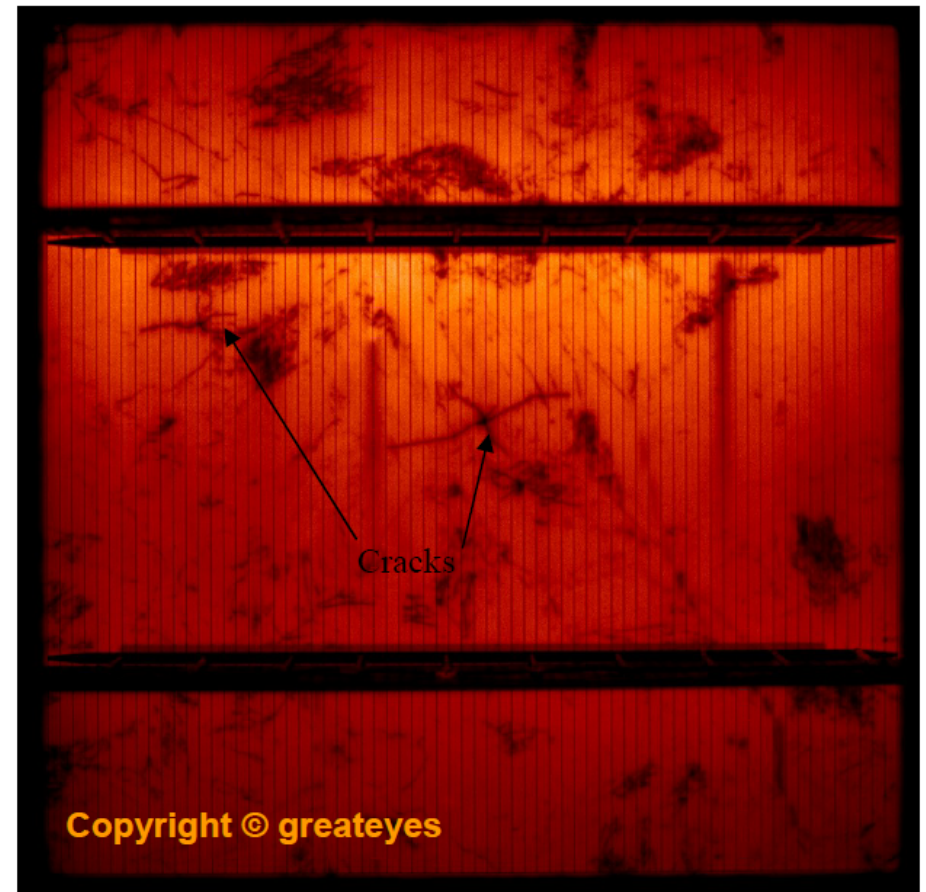
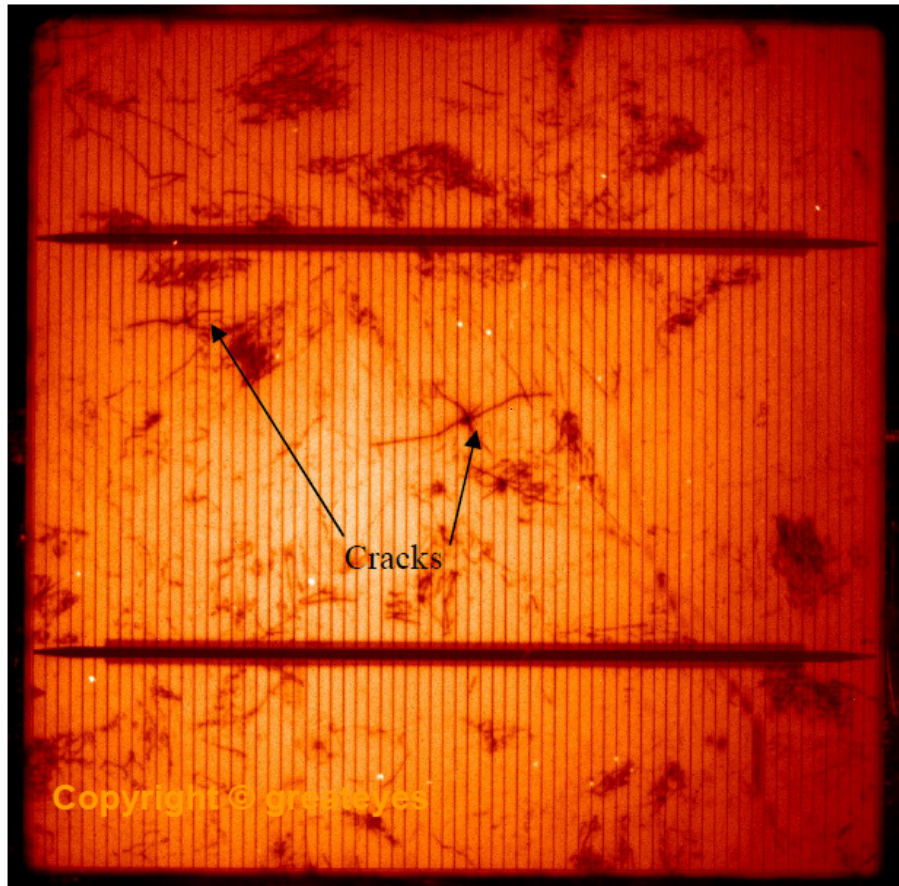


Electroluminescence of poly-Si Solar Module



Comparison of PL and EL Images

greateyes



Application of EL and PL Inspection

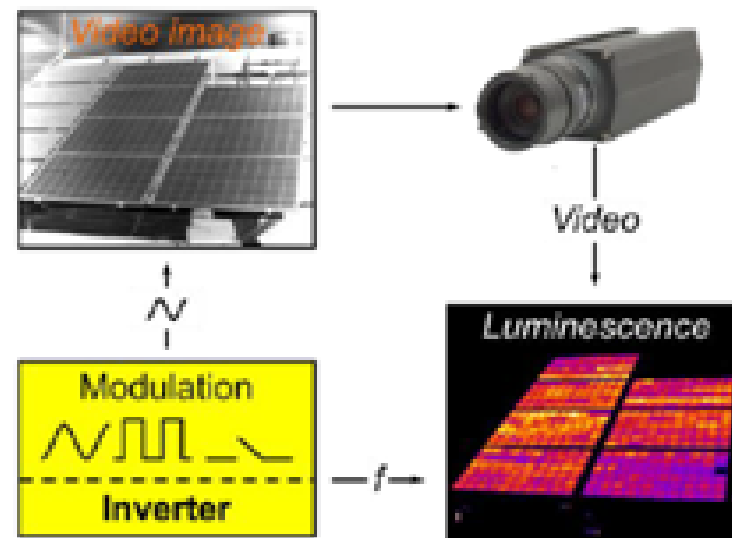
- For R&D and Production of Wafers & Solar Cells & Solar Modules
- Inspect c-Si, a-Si, CIGS, CIS, CdTe, ... photovoltaic devices
- High Informative Value (Micro Cracks, Finger defects and many more)
- Quick Measurement, Inline Process Control is possible

➡ Enhance Efficiency of Cell / Module

➡ Optimize Production Efficiency

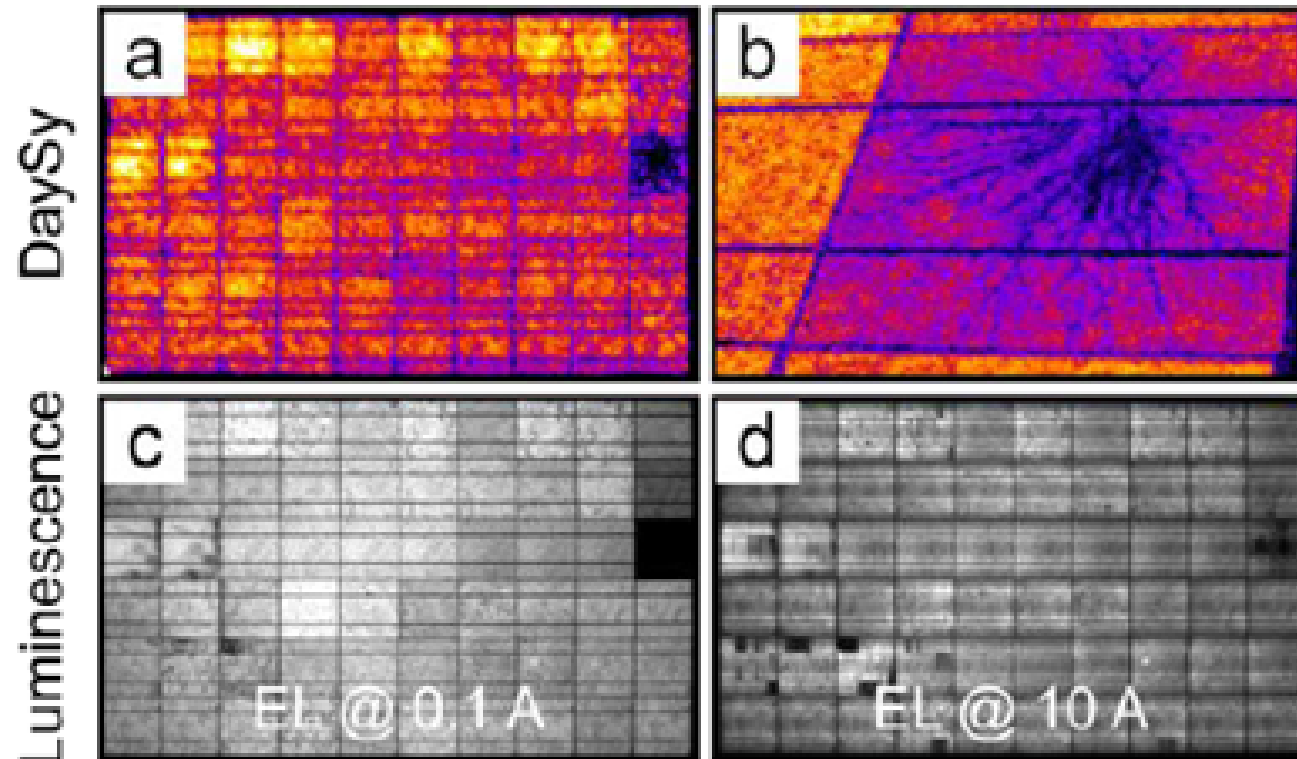
Daylight PL Imaging

- Need for lighted (daylight or artificial lighting) EL
 - Eliminates the need of a dark room.
 - Allows to capture the EL image of modules without transporting it to the lab.
- Day light Luminescence System (DaySy) method



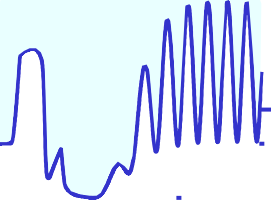
Ref: L. Stoicescu et al. "Daylight Luminescence for Photovoltaic System Testing", in Proc. 22nd International Photovoltaic Science and Engineering Conference, Hangzhou, China, 2012.

Comparison of Different Imaging Techniques

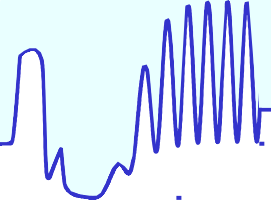


Photoluminescence

Electroluminescence



- Spectral response Measurement
- External and Internal Quantum Efficiency



- Spectral Responsivity (SR) : Amperes per Watt

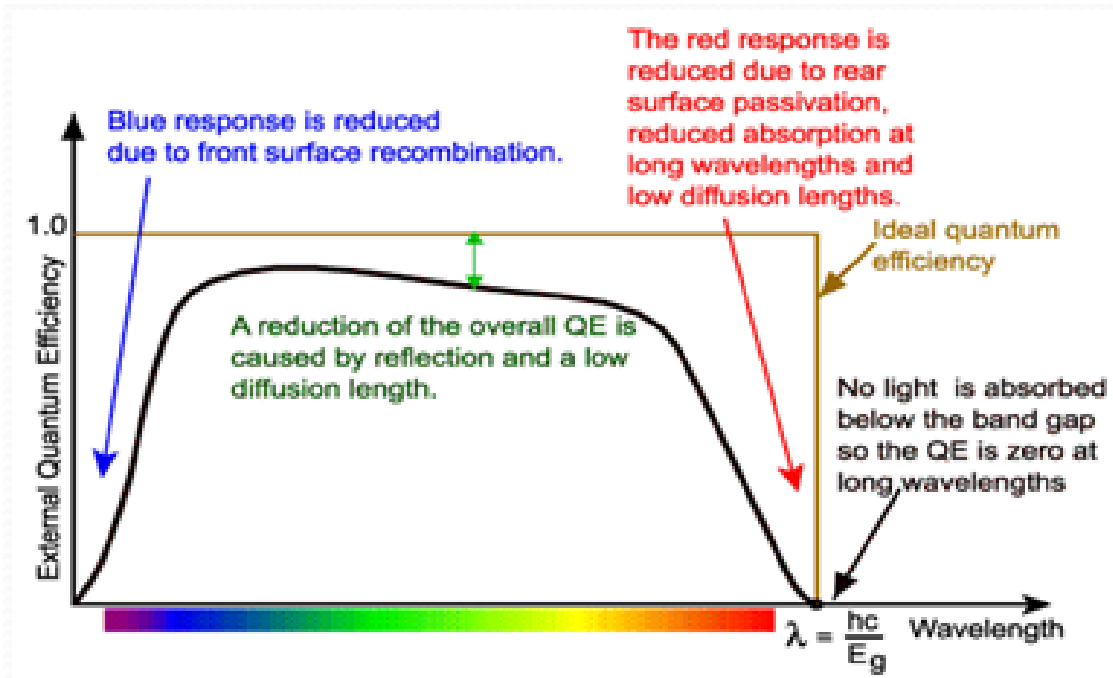
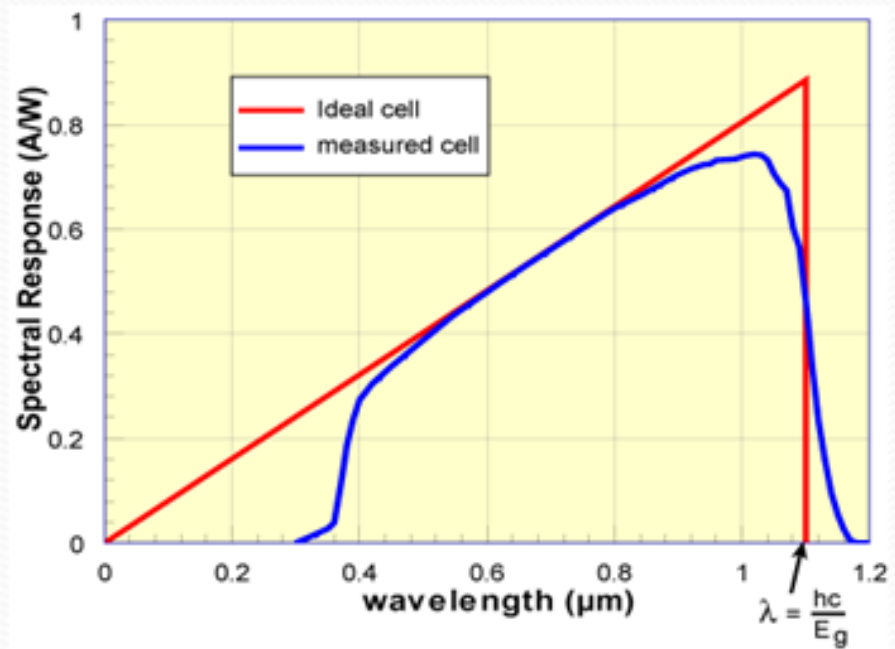
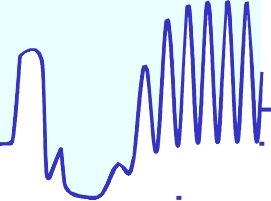
$$SR(\lambda) = I_{sc} / P_{in} \text{ (A/W)}$$

- External Quantum Efficiency (EQE) : Electrons per photon

$$\eta_{ext} = [I_{sc} / q] / [P_{in} / (hc/\lambda)] = (I_{sc}/P_{in}) [hc / \lambda q]$$

$$= SR(\lambda) [hc / q \lambda]$$

$$SR(\lambda) = (q\lambda/hc) \eta_{ext}$$



Spectral Response Measurement

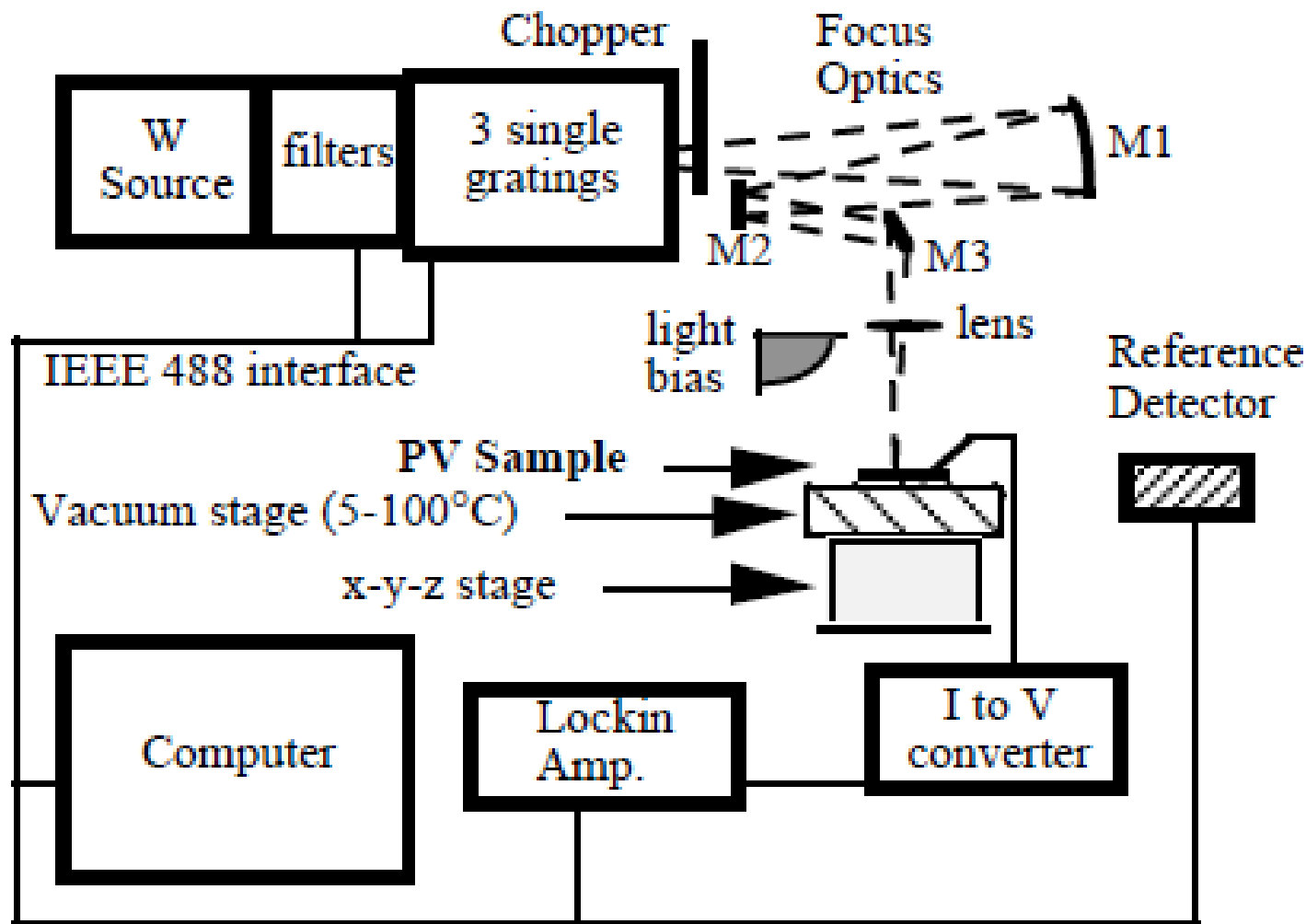


Figure 2: NREL grating monochromator QE system

K Emery et al, NREL , July 1998

Spectral Response Measurement

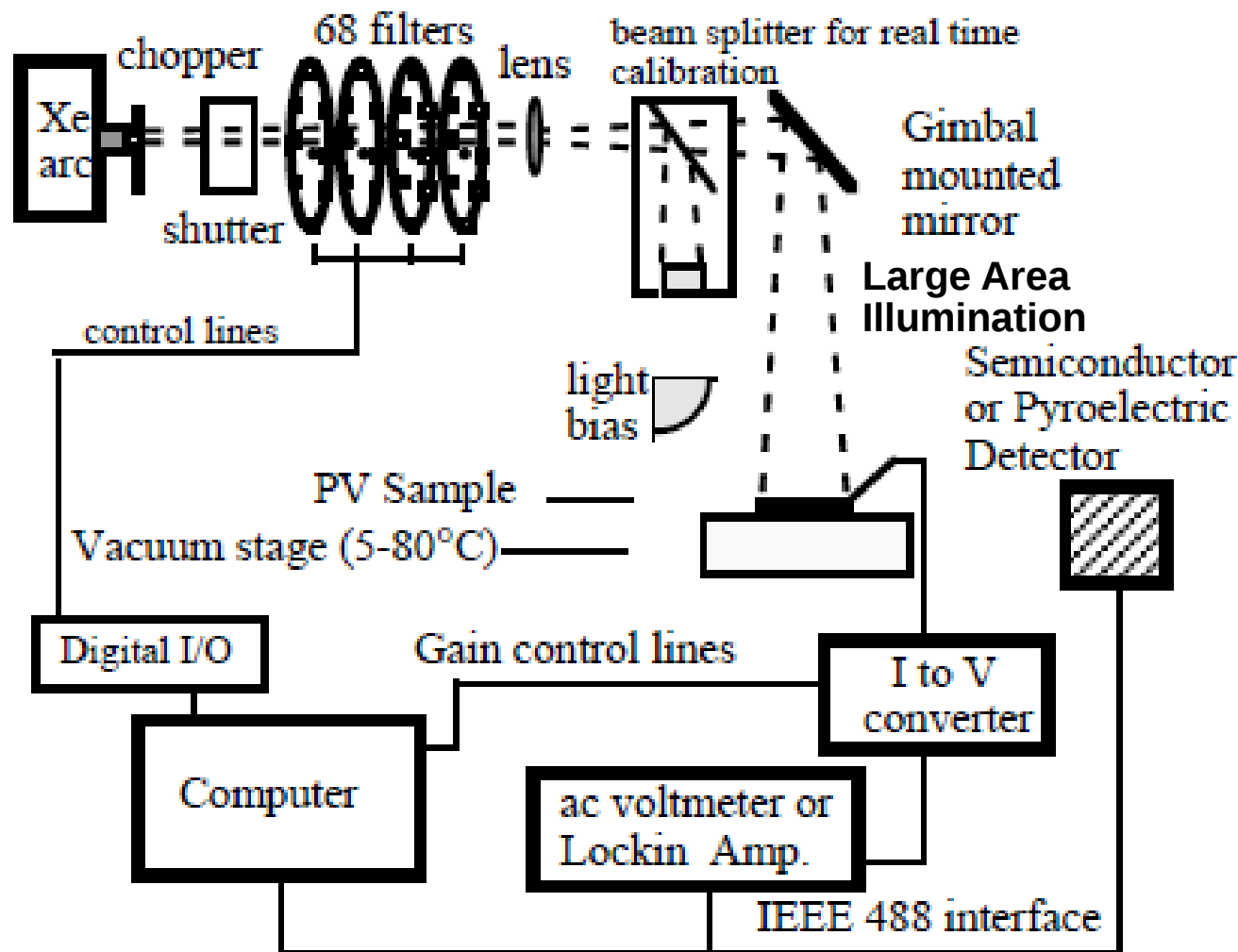


Figure 1: NREL filter QE system with a 280-2000 nm wavelength range.



Grating Based Vs Filter Based

Grating Based	Filter Based
Small Beam Size/ Small Area Illumination	Large Area illumination
Less Spatial Uniformity over large Area	Better Spatial Uniformity over large Area
Narrow Bandwidth Possible	Wider Bandwidth
Low Radiant Power	High Radiant Power

Quantum Efficiency

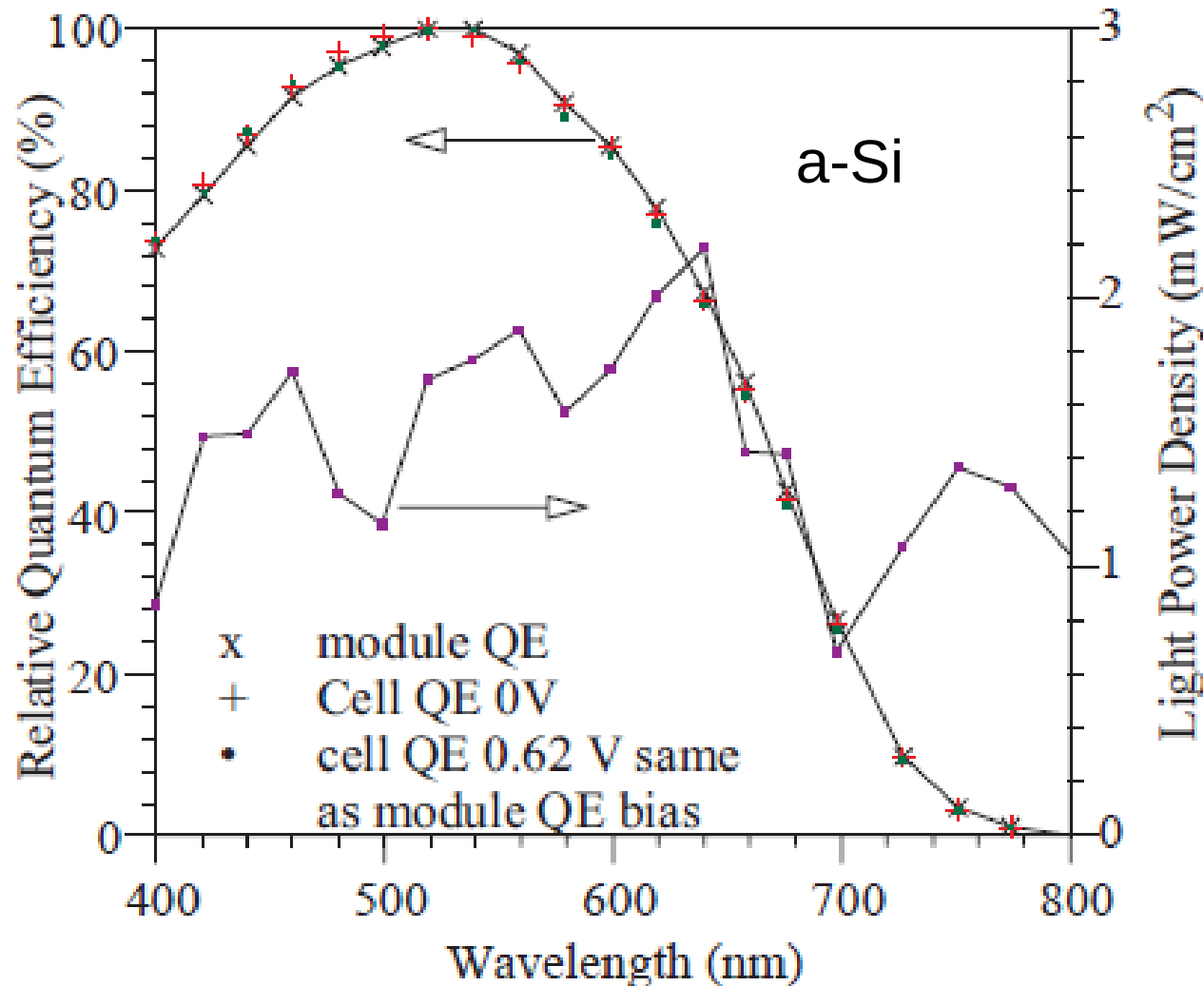


Figure 3: Module vs. cell QE measured with the filter system on a Solarex SA5 module.

Equivalent Circuit of a 2 Junction Tandem Cell

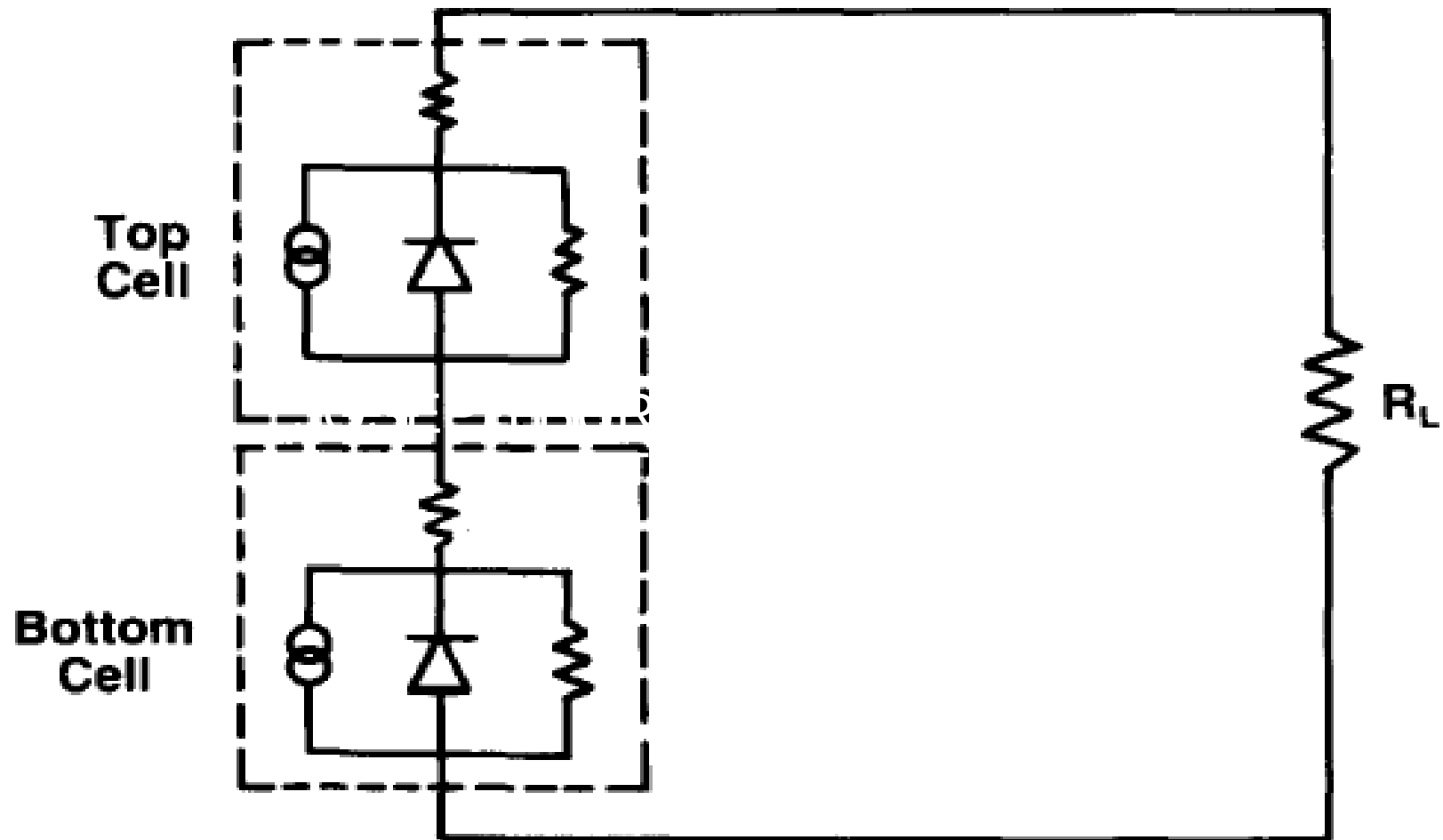


Fig. 2. Equivalent circuit of a two-cell tandem device.

Short circuit condition

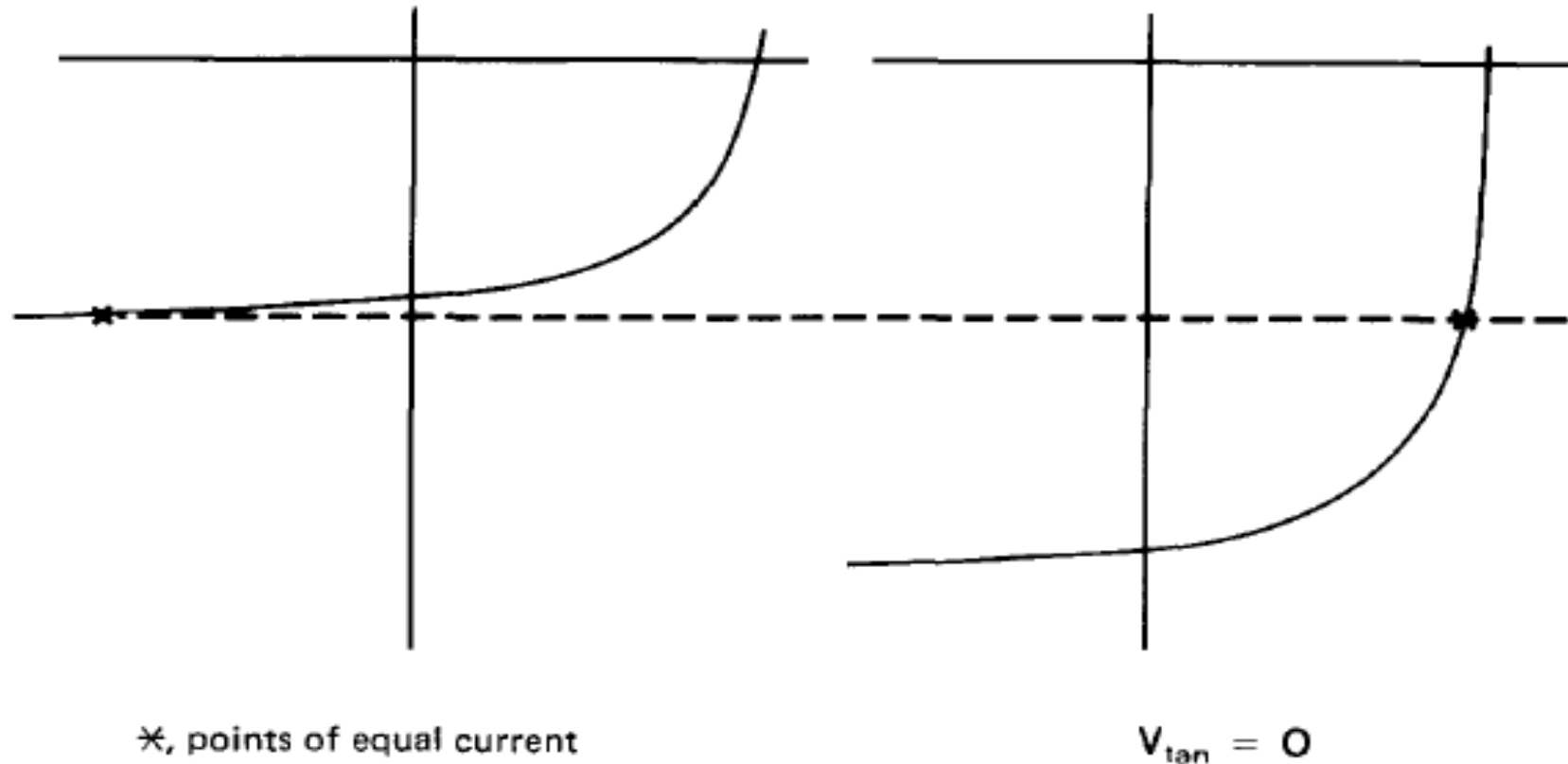


Fig. 3. Typical single-cell component I - V curves for the top and bottom cells of a tandem under illumination and at short-circuit ($V_{\text{tan}} = 0$). The individual-cell operating points are indicated by the crosses ×.

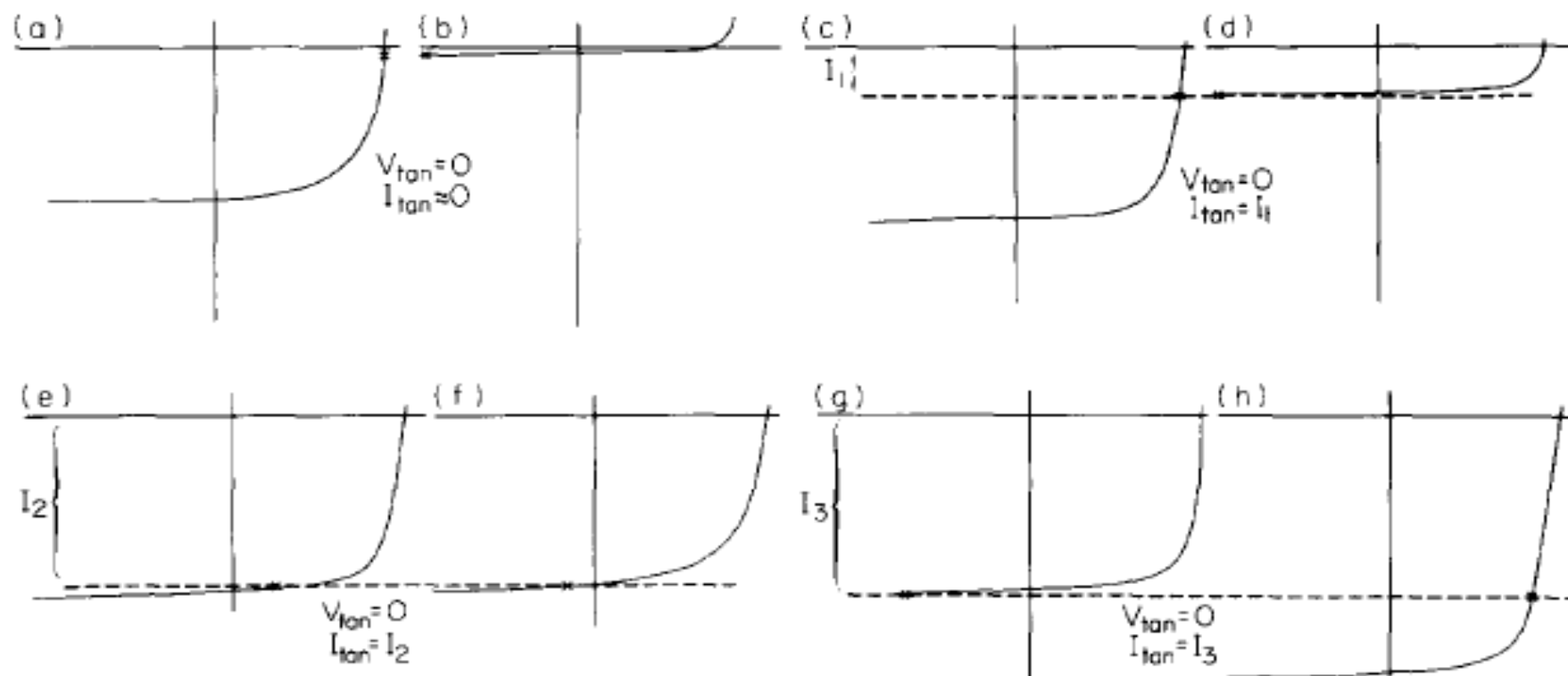


Fig. 6. Single-cell component I - V curves under blue-light bias with $V_{tan} = 0$: (a) top cell; (b) bottom cell; (c) top cell with red probe light; (d) bottom cell with red probe light; (e) top cell after increasing the red light intensity; (f) bottom cell after increasing the red light intensity; (g) top cell after further increasing the red light intensity; (h) bottom cell after further increasing the red light intensity.

Light Biasing arrangement

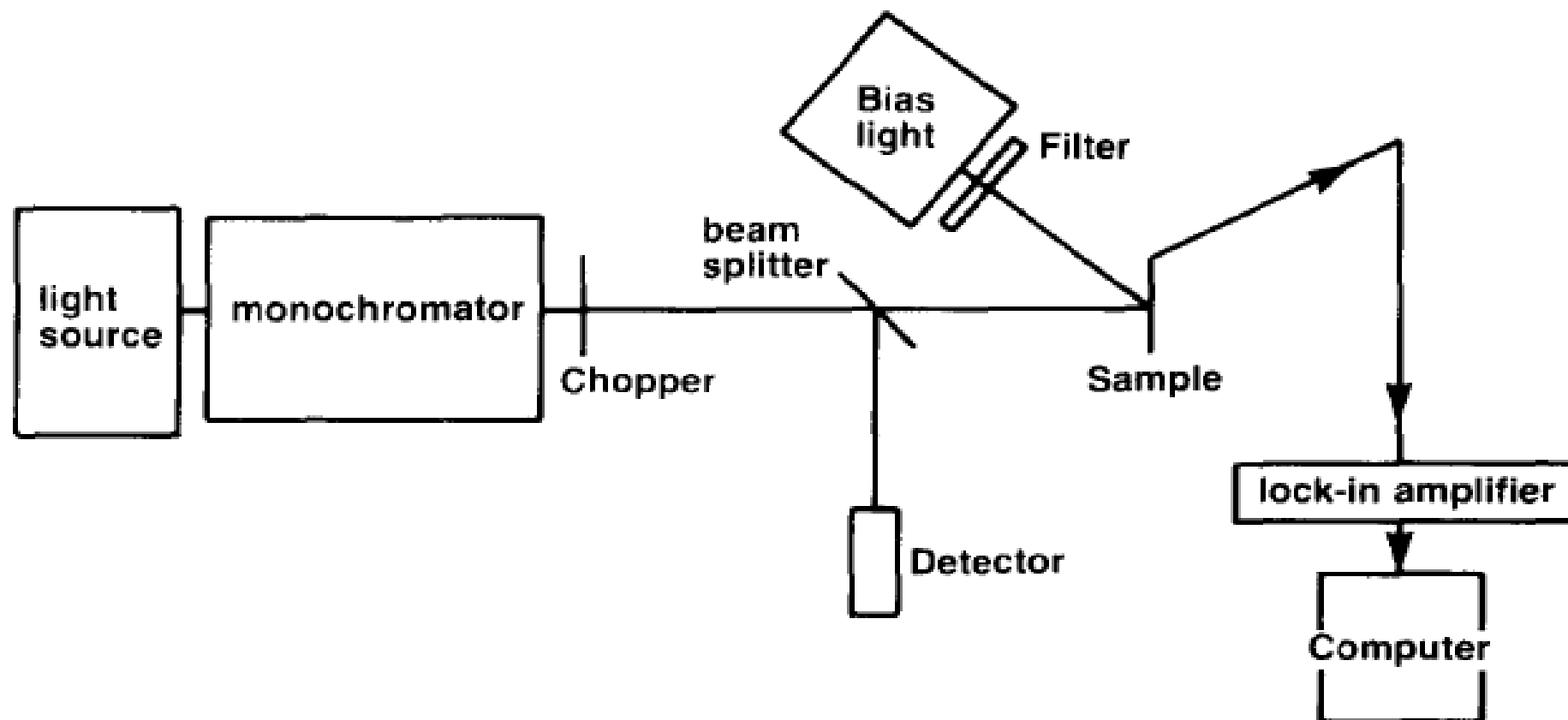


Fig. 10. Experimental setup for the quantum efficiency measurement with voltage and light biasing.

- Thermography

Shunts in Solar Cells

- The most important process-induced shunts are residues of the emitter at the edge of the cells, cracks, recombination sites at the cell edge, Schottky-type shunts below grid lines, scratches, and aluminum particles at the surface. The material-induced shunts are strong recombination sites at grown-in defects (e.g., metal-decorated small-angle grain boundaries), grown-in macroscopic Si_3N_4 inclusions, and inversion layers caused by microscopic SiC precipitates on grain boundaries crossing the wafer.

- The temperature in the shunted region is higher than in the non-shunted regions, which can be detected by Infra-red Imaging
- This technique detects the periodic local surface temperature modulation in the positions of local shunts with a sensitivity below 100 μK by applying a pulsed bias to the cell in the dark

system based on a 128128 pixel InSb focal plane array
thermocamera

Lock-in Image

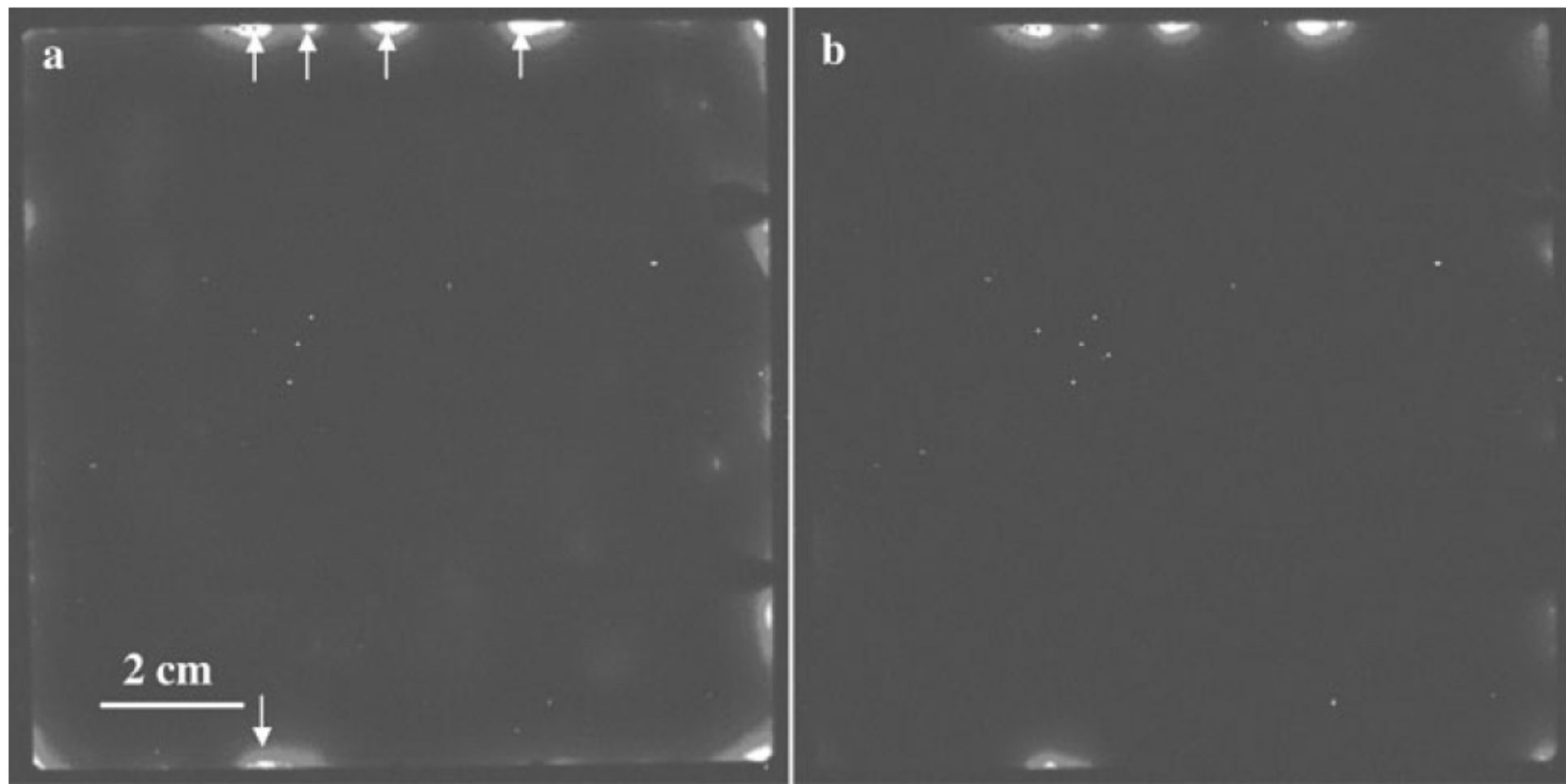


Figure 1. Lock-in thermogram of a cell containing edge shunts, measured under: (a) $+0.5$ V; (b) -0.5 V bias

Lock-in Image

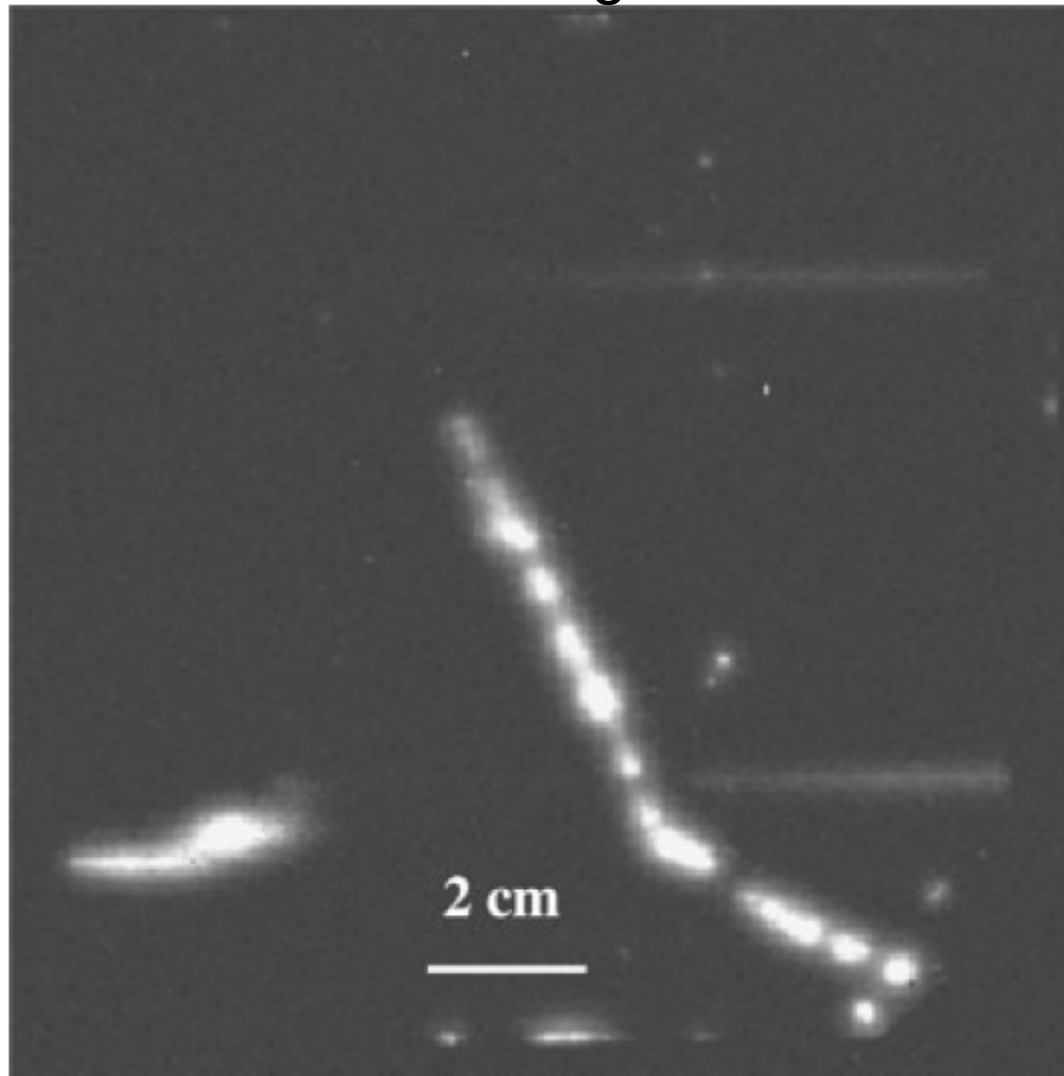


Figure 5. Lock-in thermogram of a cell with two scratches

Imaging without Lock-in

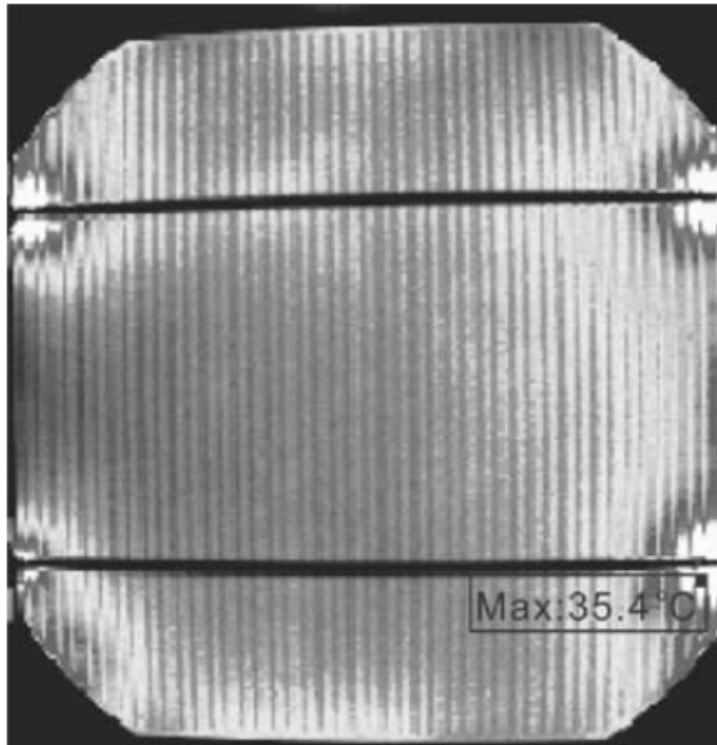


Fig. 4. Shunts caused by PECVD hooks under the four ends of bus bars.

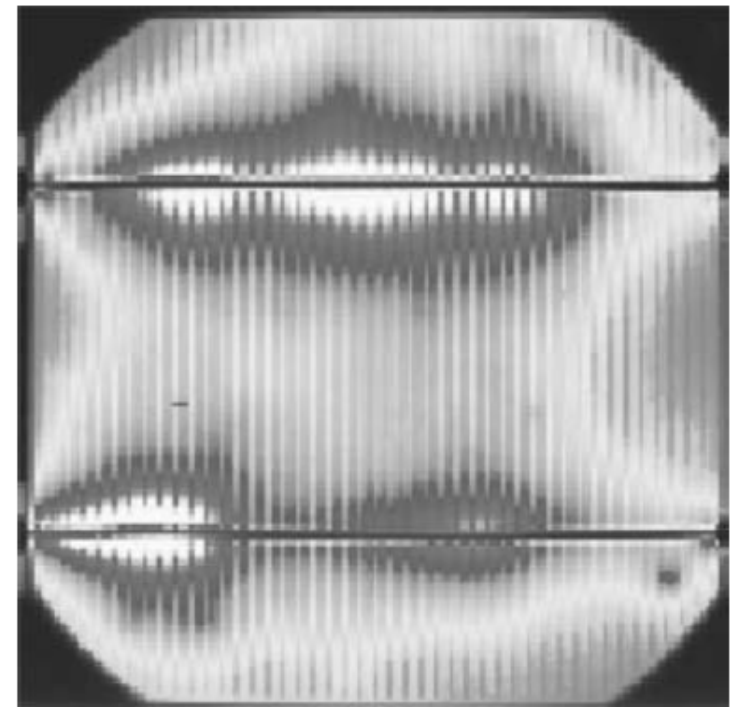


Fig. 8. Shunts caused by over sintering under the bus bars.

Z Lucheng et al, J Semiconductors 30, 076001-1 (2009)